

REMARKS

In the Office Action dated September 11, 2002, the restriction requirement was made final, and claim 16 was withdrawn from further consideration. Accordingly, claim 16 has been cancelled without prejudice to
5 the possibility of filing a divisional application directed to the subject matter of claim 16.

Claims 1-12 were rejected under 35 U.S.C. §112, second paragraph, as being indefinite for the reasons noted by the Examiner in paragraph 4 of the Office Action. Certain of claims 1-12 have been editorially amended to
10 respond to those rejections, and these changes are believed to be self-explanatory. The only clarification requested by the Examiner which has not been made, and which accordingly is traversed, is the requirement to clarify in claim 1 whether the metallized surfaces are also contact surfaces. In fact, these metallized surfaces (the surfaces 3 shown in Figure 1) are not intended
15 as contact surfaces in the sense of making contact with conductor paths on a printed circuit board. The contact surfaces 2, which are stated in claim 1 to be in a common plane, are contact surfaces which are used for that purpose, i.e., making mechanical and electrical contact between the carrier member and a printed circuit board. Nevertheless, it is not seen how claim 1 could be
20 amended in a clear manner to state that the metallized surfaces are not contact surfaces. More importantly, however, it is not seen how leaving the term "metallized surfaces" as being non-specific, as to whether those surfaces are contact surfaces, somehow renders claim 1 indefinite under the requirements of §112, second paragraph. If a claim is clear and
25 understandable and unambiguous, this is all that is required to satisfy §112, second paragraph. If this fundamental condition is satisfied, the Examiner has no statutory basis to require more specificity.

Therefore, Applicant respectfully submits that the absence of explicit language in claim 1 identifying whether the metallized surfaces are contact

surfaces or not does not make claim 1 non-compliant with regard to the requirements of §112, second paragraph.

All claims of the application are therefore submitted to be in full compliance with all provisions of §112.

5 Claims 1, 3, 4 and 10 were rejected under 35 U.S.C. §102(b) as being anticipated by Gogal. Claims 2, 5-9, 11 and 12 were rejected under 35 U.S.C. §103(a) as being unpatentable over Gogal in view of Machado. These rejections are respectfully traversed for the following reasons.

10 The carrier member set forth in claim 1 basically requires that there be at least two contact surfaces which are electrically insulated from each (the contact surfaces 2 designated with blue in the attached copy of Figure 1) and that these contact surfaces be in a common plane so as to be substantially co-planar with each other. The term "substantially co-planar" is used, and is proper, despite the requirement that these surfaces be in a common plane,
15 because it is well recognized that manufacturing tolerances will almost always preclude two surfaces from being precisely co-planar. In fact, a small amount of deviation from precise co-planarity is acceptable in the present invention, as set forth in dependent claim 10. Claim 1 has been amended to refer to the carrier member as having a carrier body, on which the contact surfaces, and
20 the other surfaces discussed below, are disposed. Moreover, this carrier body is stated to be unitary, i.e., of one piece.

 Claim 1 further states that each of the aforementioned contact surfaces has a metallized surface in electrical connection therewith, and these metallized surfaces are disposed non-parallel to the common plane in which
25 the contact surfaces are disposed. These metallized surfaces are indicated in red in the attached copy of Figure 1.

 This structure results in several advantages. The contact surfaces 2 being disposed in a common plane makes it easy to mechanically and electrically connect the inventive carrier member to a printed circuit board, via

the contact surfaces 2. For this purpose, the carrier member 1 would be flipped over from the position shown in Figure 1, so that the contact surfaces 2 are at the bottom, and then the carrier member is simply placed on the printed circuit board with the contact surfaces 2 overlying respective contact pads of conductor runs on the printed circuit board.

The surfaces 3, which are not parallel to the surfaces 2, will then proceed generally upwardly from the printed circuit board, and are available to make wire contacts with a component carrier in the interior of the carrier member, as shown in the embodiment of Figure 4. As shown in Figure 3 in the side view, multiple locations for such wire contacts are available.

The Gogal reference does not anticipate the subject matter of claim 1, nor any of claims 3, 4 and 10 depending therefrom, for several reasons. The Gogal reference does not disclose a unitary body on which the aforementioned contact surfaces are all disposed, but is composed of multiple layers of elements. Moreover, there is no element which has contact surfaces thereon and which also has metallized surfaces in electrical contact with the contact surfaces, these further metallized surfaces not being parallel to the plane containing the contact surfaces. Figure 1 of the Gogal reference is misleading because not all of the individual ceramic chips 10 through 90 are specifically shown therein. Those ceramic chips are shown in an exploded view in Figure 2. As can be seen in the exploded view of Figure 2, the only possible candidates for chip layers in Figure 2 of Gogal allegedly corresponding to the language of claim 1 would be chips 20 and 50. On those chips, however, when they are assembled to form the structure shown in Figure 1 of Gogal, the contact surfaces are not exposed at an exterior of a unitary ceramic body, as required in claim 1. Any contacts which are made by the conductor runs on the larger flat surfaces of chips 20 and 50 in the Gogal reference are completely internal connections. It is questionable whether a person of ordinary skill in the art would even characterize those internal conductor runs as being "contact surfaces."

The Gogal reference therefore does not disclose all of the elements of claim 1 as arranged and operating in claim 1, and thus does not anticipate claim 1, nor of any of claims 3, 4 and 10 depending therefrom.

5 As to the rejection of claims 2, 5-9, 11 and 12 based on the teachings of Gogal and Machado, since the Gogal reference does not disclose all of the elements of claim 1, from which each of those claims depends, modifying the Gogal reference in accordance with the teachings of Machado would not result in a structure comparable to the subject matter of any of these dependent claims. None of claims 2, 5-9, 11 or 12, therefore, would have
10 been obvious to a person of ordinary skill in the art based on the teachings of Gogal and Machado.

For the above reasons, all claims of the application are submitted to be in condition for allowance, and early reconsideration of the application is respectfully requested.

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

Please amend claim 1 as follows:

1. (Twice amended) A carrier member composed of a unitary
5 ceramic body for electronic components having at least two metallic contact
surfaces electrically insulated from one another, said contact surfaces being
disposed at an exterior of said ceramic body on a common plane of the carrier
[member] body do as to be substantially co-planar with each other and
10 available for electrical connection to a circuit board, further metallized
surfaces disposed on at least one surface of the carrier [member] body that
[does not proceed] is not parallel to the common plane of the contact
surfaces, and respective electrically conductive connections between said
metallized surfaces and said contact surfaces.

Please amend claim 2 as follows:

- 15 2. (Twice amended) A carrier member according to claim 1,
wherein the carrier [member] body comprises a base and an inductive
component disposed on an inside surface of the base .

Please amend claim 3 as follows:

- 20 3. (Twice amended) A carrier member according to claim 1
wherein [the surfaces] said at least one surface that [do] is not [proceed]
parallel to the common plane of the contact surfaces and on which the
metallized surfaces are located, [proceed] is disposed at an angle of 90°
relative to the common plane of the contact surfaces.

Please amend claim 4 as follows:

- 25 4. (Twice amended) A carrier member according to claim 1
[comprising] wherein said carrier body has two walls [proceeding] disposed at
an angle of 90° relative to the common plane of the contact surfaces. A base
disposed perpendicular to the walls and parallel to the common plane of the

contact surfaces, and two end walls that are perpendicular to the base and the walls.

Please amend claim 5 as follows:

- 5 5. (Twice amended) A carrier member according to claim 1
 wherein said carrier body has channel-shaped depressions situated between
 the metallic contact surfaces and the metallized surfaces, the channel-shaped
 depressions not being metallized.

Please amend claim 6 as follows:

- 10 6. (Twice amended) A carrier member according to claim 5,
 wherein said channel-shaped depressions are disposed on the common plane
 of the contact surfaces and comprising further channel-shaped depressions
 disposed on [the planes] said at least one surface that [do] is not [proceed]
 parallel to the common plane of the contact surfaces, said further channel-
 shaped depressions arranged on various planes forming channel edges.

15 Please amend claim 10 as follows:

10. (Twice amended) A carrier member according to claim 1
 wherein said contact surfaces [have a co-planarity of] deviate from precise co-
 planarity with each other by less than 100 μm [, whereby the co-planarity is a
 maximum spacing from a plane that lies parallel to the contact surfaces and
20 that has been calculated from the individual heights of the contact surfaces].

Please amend claim 11 as follows:

11. (Twice amended) A carrier member according to claim 1
 comprising a base [proceeding] disposed parallel to the common plane of the
 contact surfaces, and a conical frustum disposed on an inside surface of the
25 base and projecting toward an interior of said carrier [member] body.

Please amend claim 12 as follows:

12. (Twice amended) A carrier member according to claim 1 comprising a base [proceeding] disposed parallel to the common plane of the contact surfaces, and a core with a winding disposed on an inside surface of
5 the base in a direction toward an interior of said carrier [member] body.

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